

456 Series Fuse













Agency Approvals

	AGENCY	AGENCY FILE NUMBER	AMPERE RATING		
	c 'RL ° us	E10480	20A - 40A		
		T50291892	20A - 30A		
	PS	NBK030308-JP1021	20A - 30A		
	(29862	20A - 40A		

Electrical Characteristics

% of Ampere Rating	OpeningTime
100%	4 hours, Minimum
200%	60 seconds, Maximum

Description

The High Current NANO^{2®} Fuse is a small square surface mount fuse that is designed to support higher current requirements of various applications.

Features

- Surface mount high current fuse
- Fully compatible with lead-free solder alloys and higher temperature profiles associated with lead-free assembly
- RoHS compliant and Halogen Free
- Available in ratings of 20 to 40 Amperes

Applications

- Voltage regulator module for PC server
- Cooling fan system for PC server
- Storage system power
- Basestation power supply

Additional Information







Resources



Samples

Electrical Specifications

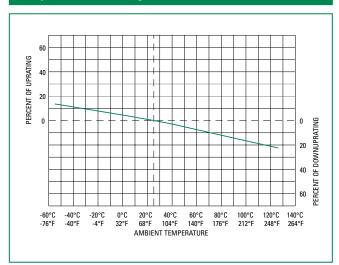
Ampere	Ampere			Nominal	Nominal	Nom Voltage	Agency Approvals			
Rating (A)	Amp Code		Interrupting Rating	Cold Resistance (Ohms)	Melting I ² t (A ² Sec.)	Drop (mV)	c AL °us	<u> </u>	PS E	® ;
20	020.	125	100A @125VAC 300A @ 65VAC 300A @ 100VDC 1000A @ 32VDC 500A @ 72VDC	0.00230	18	64.7	х	х	х	х
25	025.	125	100A @ 125VAC 300A @ 65VAC 500A @ 72VDC 1000A @ 32VDC	0.00192	45	68.38	Х	х	х	х
30	030.	125	100A @ 125VAC 300A @ 65VAC 1000A @ 32VDC 500A @ 72VDC	0.00132	81	69.9	х	х	х	х
40	040.	72	180A @ 72VDC 600A @ 60VDC	0.00105	191	55	х			х

Notes:

- 1. Cold resistance measured at less than 10% of rated current at 23°C.
- 2. Agency Approval Table Key: X=Approved or Certified, P=Pending.
- 3. I2t values stated for 1 msec opening time



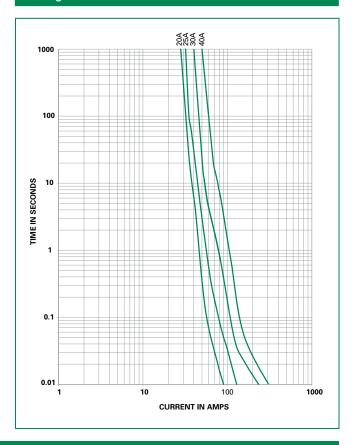
Temperature Re-rating Curve



Note

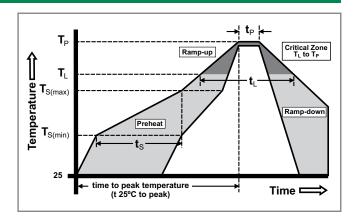
 Rerating depicted in this curve is in addition to the standard derating of 25% for continuous operation.

Average Time Current Curves



Soldering Parameters - Reflow Soldering

Reflow Co	ndition	Pb – Free assembly	
	-Temperature Min (T _{s(min)})	150°C	
Pre Heat	-Temperature Max (T _{s(max)})	200°C	
	-Time (Min to Max) (t _s)	60 – 180 secs	
Average ra	amp up rate (LiquidusTemp k	5°C/second max.	
T _{S(max)} to T _I	- Ramp-up Rate	5°C/second max.	
Reflow	-Temperature (T _L) (Liquidus)	217°C	
nellow	-Temperature (t _L)	60 – 150 seconds	
PeakTemp	erature (T _P)	260+0/-5 °C	
Time with Temperatu	in 5°C of actual peak ure (t _p)	20 – 40 seconds	
Ramp-dov	vn Rate	5°C/second max.	
Time 25°C	to peakTemperature (T _P)	8 minutes max.	
Do not exc	ceed	260°C	



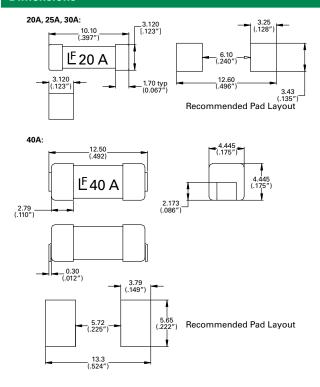


Product Characteristics

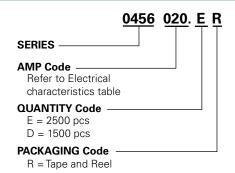
Materials	Body: Ceramic Cap: Silver Plated Brass		
Product Marking	Body: Brand Logo, Current Rating		
Insulation Resistance	MIL-STD-202, method 302, Test Condition A (10,000 ohms, Minimum)		
Solderability	MIL-STD-202, Method 208		
Resistance to Soldering Heat	MIL-STD-202, Method 210, Test Condition B (10 sec at 260°C)		
	Min. copper layer thickness = 100µm Min. copper trace width =20A, 30 10mm (20A, 30A) / 15mm (40A)		
PCB Recommendation for Thermal Management	Alternate methods of thermal management may be used. In such cases, under normal operations, the maximum temperature of the fuse body should not exceed 90°C in a 25°C environment.		

Operating Temperature	-55°C to 125°C with proper derating		
Thermal Shock	MIL-STD-202, Method 107, Test Condition B (5 cycles -65°C to 125°C)		
Vibration	MIL-STD-202, Method 201 (10-55 Hz)		
Moisture Sensitivity Level	J-STD-020, Level 1		
Moisture Resistance	MIL-STD-202 Method 106, High Humidity (90-98%RH), Heat (65°C)		
Salt Spray	MIL-STD-202, Method 101, Test Condition B		
Mechanical Shock	MIL-STD-202, Method 213, Test Condition I (100 G's peak for 6 milliseconds)		

Dimensions



Part Numbering System



Packaging

Rating	Packaging Option	Packaging Specification	Quantity	Quantity & Packaging Code
20A, 25A, 30A	24 mm Tape and Reel	EIA RS-481-2	2500	ER
40A	24 mm Tape and Reel	EIA RS-481-2 (IEC 286, part 3)	1500	DR